

**What Is Claimed Is:**

1. A grounding cable, comprising:
  - a first grounding wire;
  - a first outer cover surrounding the first grounding wire and made of an insulating material;
  - a second grounding wire enclosing the first outer cover; and
  - a second outer cover surrounding the second grounding wire.
2. The grounding cable according to claim 1, wherein the second grounding wire has a mesh structure.
3. The grounding cable according to claim 1, wherein the first and second grounding wires is made of a metal material and the metal material includes one of copper, copper coated with nickel and an alloy of copper and nickel.
4. The grounding cable according to claim 1, wherein the first and second outer covers include polyvinyl chloride (PVC).
5. A semiconductor manufacturing apparatus using grounding cables, comprising:
  - a chamber;
  - a plasma generating source including a first electrode in the chamber, a first power supplier and a first impedance matching device out of the chamber;
  - a bias source including a second electrode in the chamber, a second power

supplier and a second impedance matching device out of the chamber; and first, second, third, fourth and fifth grounding cables, each of the grounding cables connected to the first and second power suppliers, the first and second impedance matching devices and the chamber, respectively, each of the grounding cables including:

a first grounding wire;

a first outer cover surrounding the first grounding wire and made of an insulating material;

a second grounding wire enclosing the first outer cover; and

a second outer cover surrounding the second grounding wire.

6. The apparatus according to claim 5, wherein the second grounding wire has a mesh structure.

7. The apparatus according to claim 5, wherein the first and second grounding wires include one of copper, copper coated with nickel and an alloy of copper and nickel.

8. The apparatus according to claim 5, wherein the first and second outer covers include polyvinyl chloride (PVC).